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April 2015

FDBL0210N80

N-Channel PowerTrench® MOSFET **80 V, 240 A, 2.0 m**Ω

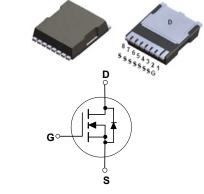
Features

- Typical $R_{DS(on)}$ = 1.5 mΩ at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{q(tot)}$ = 130 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant

Applications

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automations
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





For current package drawing, please refer to the Fairchild website at http://www.fairchildsemi.com/dwg/PS/PSOF08A.pdf.

MOSFET Maximum Ratings $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Ratings	Units	
V_{DSS}	Drain-to-Source Voltage		80	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	240	A
ID	Pulsed Drain Current	T _C = 25°C	See Figure 4	A
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	512	mJ
D	Power Dissipation		357	W
P_{D}	Derate Above 25°C		2.38	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.42	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

- 1: Current is limited by silicon.
- Starting T_J = 25°C, L = 0.25mH, I_{AS} = 64A, V_{DD} = 80V during inductor charging and V_{DD} = 0V during time in avalanche.
 R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDBL0210N80	FDBL0210N80	MO-299A	-	-	-

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Units

Max.

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted.

Parameter

Off Characteristics								
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	80	-	-	V		
,	Drain-to-Source Leakage Current	$V_{DS} = 80V$, $T_{J} = 25^{\circ}C$	-	-	1	μΑ		
IDSS		$V_{GS} = 0V$ $T_J = 175^{\circ}C$ (Note 4)	-	-	1	mA		
I _{GSS}	Gate-to-Source Leakage Current	V _{GS} = ±20V	-	-	±100	nA		

Test Conditions

Min.

Тур.

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	3.0	4.0	V
R _{DS(on)}	Drain to Source On Resistance	I _D = 80A,	$T_{J} = 25^{\circ}C$	-	1.5	2.0	mΩ
		V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	3.1	4.1	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	- V _{DS} = 40V, V _{GS} = 0V, - f = 1MHz		-	10000	-	pF
C _{oss}	Output Capacitance			-	1540	-	pF
C _{rss}	Reverse Transfer Capacitance			-	70	-	pF
R_g	Gate Resistance	f = 1MHz		-	2.8	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	$V_{GS} = 0 \text{ to } 10V$ $V_{DD} = 64V$ $I_{D} = 80A$		-	130	169	nC
$Q_{g(th)}$	Threshold Gate Charge			-	18	27	nC
Q_{gs}	Gate-to-Source Gate Charge		_	-	47	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge			-	24	-	nC

Switching Characteristics

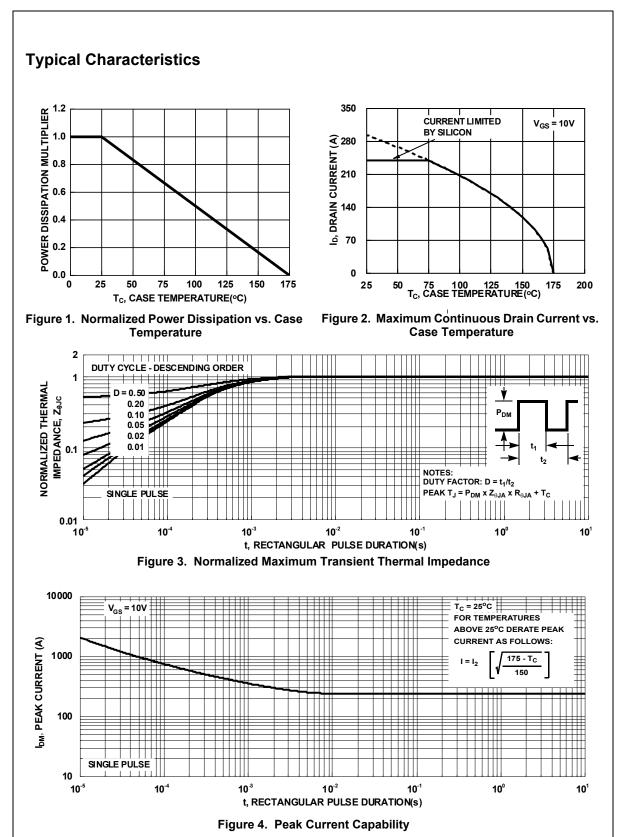
t _{on}	Turn-On Time		-	-	133	ns
t _{d(on)}	Turn-On Delay		-	39	-	ns
t _r	Rise Time	V _{DD} = 40V, I _D = 80A,	-	63	-	ns
t _{d(off)}	Turn-Off Delay	V_{GS} = 10V, R_{GEN} = 6Ω	-	61	-	ns
t _f	Fall Time		-	33	-	ns
t _{off}	Turn-Off Time		-	-	140	ns

Drain-Source Diode Characteristics

V _{SD}	Source-to-Drain Dioge Voltage	I _{SD} =80A, V _{GS} = 0V	-	-	1.25	V
		$I_{SD} = 40A, V_{GS} = 0V$	-	-	1.2	V
t _{rr}	Reverse-Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	83	108	ns
Q _{rr}	Reverse-Recovery Charge	V _{DD} =64V	-	118	153	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.



Typical Characteristics 2000 1000 If R = 0 $t_{AV} = (L)(I_{AS})/(1.3*RATED BV_{DSS} - V_{DD})$ 1000 € DRAIN CURRENT (A) $t_{AV} = (L/R)ln[(l_{AS}*R)/(1.3*RATED BV_{DSS} - V_{DD}) +1]$ AS, AVALANCHE CURRENT 100 100 10 STARTING T_J = 25°C OPERATION IN THIS AREA MAY BE LIMITED BY IDS (on) ئے SINGLE PULSE TJ = MAX RATED TC = 25°C 100ms 0.1 0.001 100 0.01 10 1000 0.1 10 100 tav, TIME IN AVALANCHE (ms) V_{DS}, DRAIN TO SOURCE VOLTAGE (V) NOTE: Refer to Fairchild Application Notes AN7514 and AN7515 Figure 5. Forward Bias Safe Operating Area Figure 6. Unclamped Inductive Switching Capability 350 400 PULSE DURATION = 80 µs IS, REVERSE DRAIN CURRENT (A) DUTY CYCLE = 0.5% MAX 300 V_{GS} = 0 V 100 V_{DD} = 5V € , DRAIN CURRENT (001 120 100 220 250 T_J= 175 °C 10 $T_J = 25^{\circ}C$ $T_J = 25$ °C T_J = -55°C $T_J = 175^{\circ}C$ ف 50 0.1 0.0 0.2 0.4 0.6 8.0 1.0 1.2 V_{GS}, GATE TO SOURCE VOLTAGE (V) V_{SD}, BODY DIODE FORWARD VOLTAGE (V) Figure 7. Transfer Characteristics Figure 8. Forward Diode Characteristics 350 350 VGS V_{GS} €300 €300 10V 8V 10V DRAIN CURRENT (0 00 02 05 00 05 05 7V 7V 5V 80μs PULSE WIDTH 80µs PULSE WIDTH Tj=25°C ڡٛ Tj=175°C 50 50 0 0 Figure 9. Saturation Characteristics Figure 10. Saturation Characteristics

Typical Characteristics

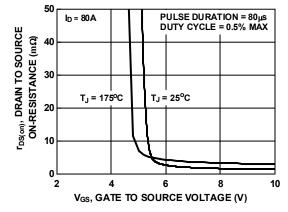


Figure 11. R_{DSON} vs. Gate Voltage

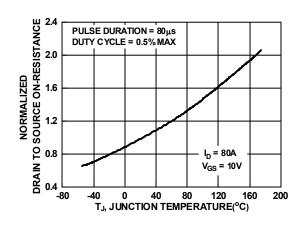


Figure 12. Normalized R_{DSON} vs. Junction Temperature

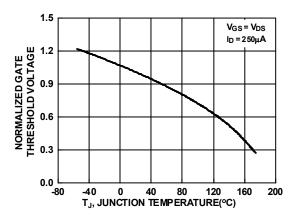


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

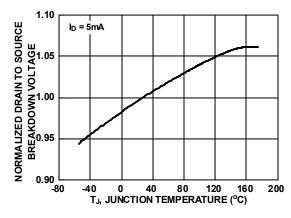


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

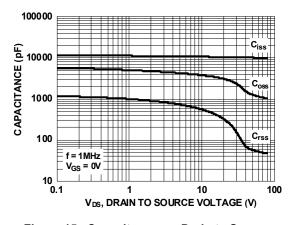


Figure 15. Capacitance vs. Drain to Source Voltage

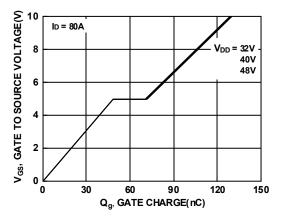
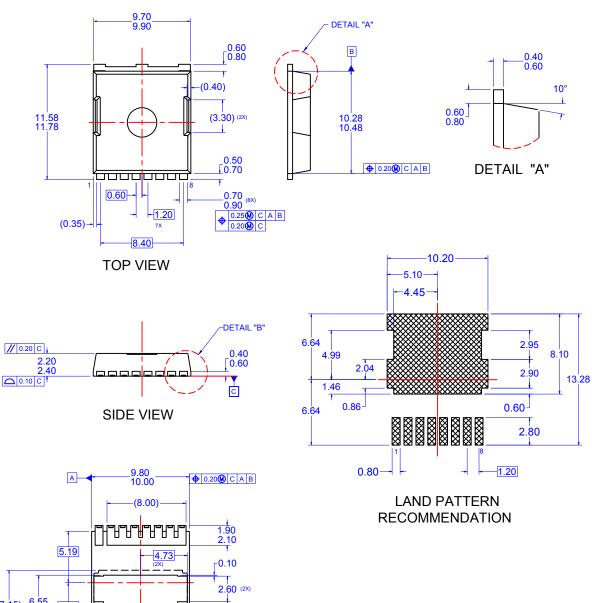


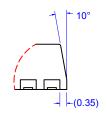
Figure 16. Gate Charge vs. Gate to Source Voltage



NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE A, DATED NOVEMBER 2009.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: MKT-PSOF08AREV3

BOTTOM VIEW



DETAIL "B"

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